

IEEE P802.3ck Interim meeting – September 22, 2021

Prepared by Kent Lusted

Proposed Agenda:

- Approval of the Agenda
- Approval of Sept. 9th minutes
- IEEE Patent Policy reminder
- IEEE Copyright reminder
- IEEE Participation Requirements reminder
- Task Force Status
- Chief Editor's Report
- Technical Presentations
 - “What should the CTLE range be for Chip to Module?”, Mike Dudek
 - “Improved MDI Connector Mapping”, Ali Ghiasi
 - “D2.1 Discussions carrying over; Host output Swing/Peak”, Beth Kochuparambil, Adees Ran
 - “TP2 J3u Value”, John Calvin (late)

Presentations posted at: <http://www.ieee802.org/3/ck/public/adhoc/index.html>

Meeting began at ~07:05 a.m. Pacific by Beth Kochuparambil.

Meeting began with the agenda presentation:

https://www.ieee802.org/3/ck/public/adhoc/sept22_21/agenda_092221a_3ck_adhoc.pdf

The ad hoc chair reminded participants to indicate full names and employer/affiliation correctly for the meeting minutes. Reminded participants to mute lines when not speaking and reviewed the steps to unmute. She also indicated that attendance was to be taken via webex participant's list for the purpose of the minutes.

Presented the proposed agenda. Chair noted that the minutes item should be “September 8” instead of “September 9”. Chair asked if there was modification or opposition to the agenda. No one responded. The agenda was approved by the ad hoc.

The minutes for the September 8 ad hoc meeting were posted to the website. (see: https://www.ieee802.org/3/ck/public/adhoc/sept08_21/minutes_090821_3ck_adhoc.pdf) Chair asked if there were modifications or corrections to the posted minutes. No one responded. Minutes were approved.

Chair reviewed the slide with the Participation requirements.

Chair asked if anyone participating had not read the copyright slide set – no one responded. Chair showed the IEEE-SA copyright slides.

Chair asked if anyone participating had not read the patent slide set – no one responded. Chair showed the patent policy slides and made a call for Potentially Essential Patents – no one responded.

Chair reviewed the ground rules.

Chair called for members of the press. No one responded.

Agenda Items

P802.3ck Update, Beth Kochuparambil

See: https://www.ieee802.org/3/ck/public/adhoc/sept22_21/agenda_092221a_3ck_adhoc.pdf

- Draft 2.2 Working Group ballot recirculation closed on Friday, 17 September 2021.
- There were 162 comments from 13 contributors
- Noted that the D2.2 comment resolution series would be extended to add extra time on 5/6 October and extra sessions on 19/20 October.
- Reminded participants of the IEEE 802.3 Working Group meeting on 30 September.

Preliminary Chief Editor's Report, Matt Brown

See: https://www.ieee802.org/3/ck/public/adhoc/sept22_21/brown_3ck_adhoc_01_092221.pdf

- The Chief Editor thanked the editorial team for their hard work.
- The comment count for D2.1 in the chart on slide 5 does not include the D2.1 late comments.
- It was noted there were several D2.2 comments that were restatements of comments against previous drafts.

Presentation #1:

“What should the CTLE range be for Chip to Module?”, Mike Dudek

See: https://www.ieee802.org/3/ck/public/21_09/dudek_3ck_01_0921.pdf

- It was noted that the presentation is related to comment #72 against D2.2
- On slide 5, it was noted that a host PCB loss greater than 325mm with the 30 mm package would exceed the transition time specifications.
- Discussed the proposed gDC values against the allowed host insertion loss specifications.
- Chair asked participants to provide feedback to the author prior to comment resolution.

Presentation #2:

“Improved MDI Connector Mapping”, Ali Ghiasi

See: https://www.ieee802.org/3/ck/public/21_09/ghiasi_3ck_01_0921.pdf

- It was noted that the GND signals could be added to the proposed table.
- Chair asked participants to provide feedback to the author prior to comment resolution.

Chair noted that there was a late contribution from John Calvin. Chair asked if there was opposition to hearing the late contribution. No one responded.

Presentation #3:

“D2.1 Discussions carrying over; Host output Swing/Peak”, Beth Kochuparambil and Adees Ran

See:

https://www.ieee802.org/3/ck/public/adhoc/sept22_21/kochuparambil_3ck_adhoc_01_092221.pdf

- Discussed the differential peak-to-peak specification as it relates to the PRBS13Q pattern.

Chair reminded participants to sign into the IEEE Meeting Attendance Tool to get Working Group attendance credit.

Presentation #4:

“TP2 J3u Value”, John Calvin

See: https://www.ieee802.org/3/ck/public/adhoc/sept22_21/calvin_3ck_adhoc_01_092221.pdf

- Discussed the assumed loss budget math. There was a request for offline discussion to investigate possible sources of error.

Chair noted that decisions will need to be taken during comment resolution on the subjects raised in the presentations.

Chair reminded participants that the adjusted calendar invites for comment resolution would be sent via the email reflector. Also that the posted proposed comment responses and comment agenda would be sent via the email reflector.

Chair noted that the next meetings were Tuesday and Wednesday, 28 and 29 September. The meeting on 27 September overlaps with the IEEE 802.3 Beyond 400 Gb/s Study Group. John D’Ambrosia noted that the Study Group would only be considering liaison responses at the Study Group meeting.

The ad hoc meeting ended at ~9:05 am Pacific.

List of attendees (captured from Webex tool)

Name	Affiliation	Employed by
Adam Healey	Broadcom	Broadcom
Adee Ran	Cisco	Cisco
Alan Kinningham	I-PEX	I-PEX
Alex Haser	Molex	Molex
Ali Ghiasi	Ghiasi Quantum/Inphi	Ghiasi Quantum/Inphi
Arthur Marris	Cadence	Cadence
Ayal Shoal	Synopsys	Synopsys
Beth Kochuparambil	Cisco	Cisco
Bill Simms	NVIDIA	NVIDIA
Blake Brown	UNH-IOL	UNH-IOL
Bruce Champion	TE Connectivity	TE Connectivity
Champion (Chien Ping) Kao	Cornelis Networks	Cornelis Networks
Chris DiMinico	PHY-SI	PHY-SI
Christian Neulinger	MD Elektronik	MD Elektronik
Claus Hoyer	Xena Networks	Xena Networks
Curtis Donahue	Rohde & Schwarz	Rohde & Schwarz
Dave Estes	Spirent	Spirent
David Malicoat	Senko	Independent
David Ofelt	Juniper	Juniper
David Piehler	Dell EMC	Dell EMC

Ed Ulrichs	Intel	Intel
Edward Nakamoto	Spirent	Spirent
Eugene Opsasnick	Broadcom	Broadcom
Frank Chang	Source Photonics	Source Photonics
Gary Nicholl	Cisco	Cisco
Geoff Zhang	Xilinx	Xilinx
Guangcan Mi	Huawei	Huawei
Hai-Feng Liu	HG Genuine	HG Genuine
Hansel Dsilva	Achronix	Achronix
Harisankar Aravind	Astera Labs	Astera Labs
Hossein Sedarat	Ethernovia	Ethernovia
Howard Heck	Intel	Intel
Istvan BakroNagy	EFFECT Photonics	EFFECT Photonics
James Weaver	Arista	Arista
James Young	Commscope	Commscope
Jamila Josip Borda	BMW	BMW
Jane Lim	Cisco	Cisco
Jeff Slavick	Broadcom	Broadcom
Jeffery Maki	Juniper	Juniper
Jim Theodoras	HG Genuine	HG Genuine
Jinhua Chen	Luxshare ICT	Luxshare ICT
Jodi Haasz	IEEE SA	IEEE SA
John Calvin	Keysight	Keysight

John D'Ambrosia	Futurewei (US Subsidiary of Huawei)	Futurewei
John Ewen	Marvell	Marvell
John Yurtin	Aptiv	Aptiv
Jonathan Ingham	Broadcom	Broadcom
Joshua Kim	Hirose	Hirose
Karl Bois	TE Connectivity	TE Connectivity
Kent Lusted	Intel	Intel
Kumaran Krishnasamy	Broadcom	Broadcom
Liav Ben-Artzi	Marvell	Marvell
Lu-Vong Phan	ZT Systems	ZT Systems
Mark Kimber	Semtech	Semtech
Mark Nowell	Cisco	Cisco
Matt Brown	Huawei	Huawei
Mau-Lin Wu	Mediatek	Mediatek
Mike Dudek	Marvell	Marvell
Mike Li	Intel	Intel
Nathan Tracy	TE Connectivity	TE Connectivity
Patrick Cui	Source Photonics	Source Photonics
Paul Brooks	Viavi	Viavi
Pavel Zivny	Tektronix	Tektronix
Pavel Zivny	Tektronix	Tektronix
Phil Sun	Credo	Credo

Piers Dawe	NVIDIA	NVIDIA
Pirooz Toyserkani	Cisco	Cisco
Qingya She	Fujitsu	Fujitsu
Rajmohan Hegde	Broadcom	Broadcom
Rich Mellitz	Samtec	Samtec
Rick Rabinovich	Keysight	Keysight
Ryan Latchman	Macom	Macom
Sam Kocsis	Amphenol	Amphenol
Scott Sommers	Molex	Molex
Scott Walley	Max Linear	Max Linear
Semmy Peng	Huawei	Huawei
Shayan Shahramian	Alphawave	Alphawave
Sheng Zhang	Source Photonics	Source Photonics
Shimon Muller	Axalume	Axalume
Steve Sekel	Wilder Tech	Wilder Tech
Tao Hu	Marvell	Marvell
Terry Little	Foxconn Interconnect	Foxconn Interconnect
Tobey PR Li	Mediatek	Mediatek
Tom Palkert	Macom/Samtec	Macom/Samtec
Tom Souvignier	Broadcom	Broadcom
Toshiaki Sakai	Socionext	Socionext
Varun Garg	Keysight	Keysight
Viet Tran	Keysight	Keysight

Xiang He	Huawei	Huawei
Yan Zhuang	Huawei	Huawei
Yasuo Hidaka	Credo	Credo